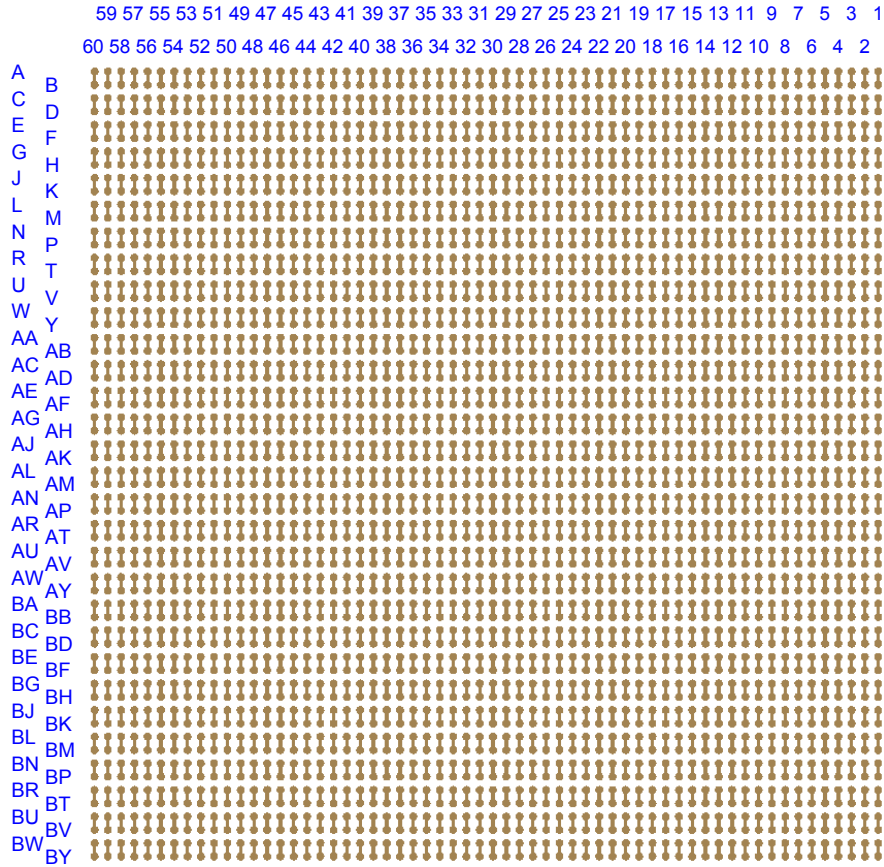


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.305mm (12 MIL).
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.28mm (11 MIL).
 - 5) PAD Cu DIAMETER: 0.355mm (14 MIL).
 - 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT or Polyimide).
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
LPGA3600T.5C-DC609	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LPGA3600T.5C-DC609D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LPGA3600T.5-DC609	Sn63/Pb37	NO	NO	NO
LPGA3600T.5-DC609D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE				
DRAWN	T. Au	10/30/2013				
ENG	M. Hart	10/30/2013	TITLE		LPGA3600T.5-DC609 DAISY CHAIN DUMMY	
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			2.9:1	A	556091	A
CUST			DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED						

BALL VIEW



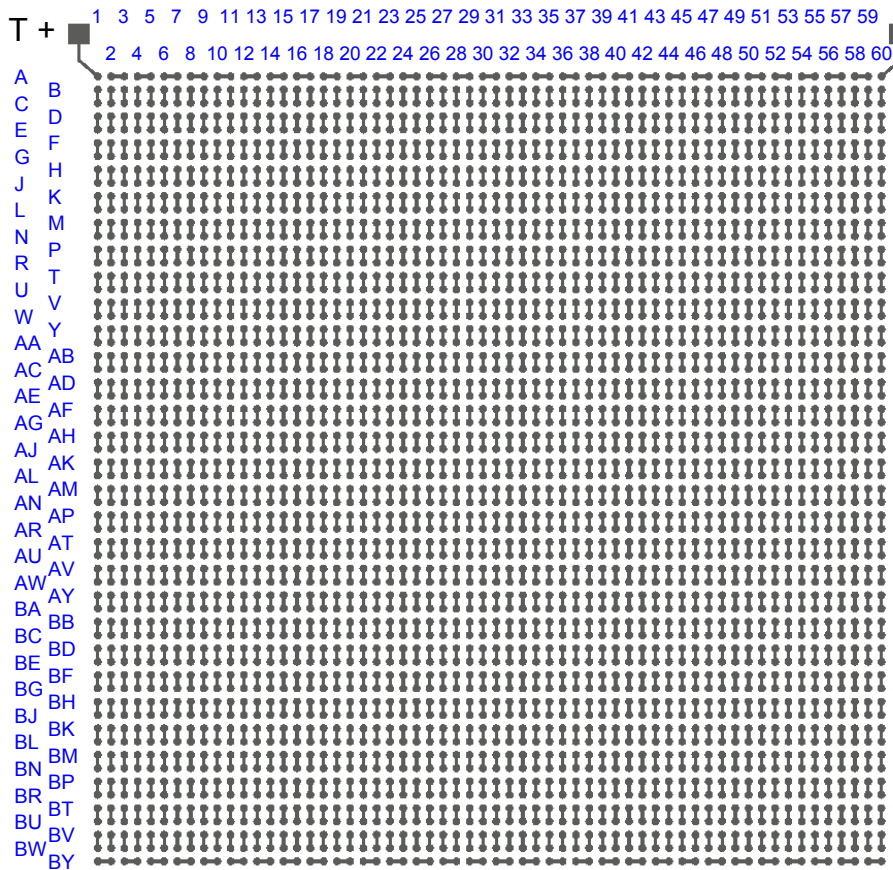
BOTTOM SIDE (TOP X-RAY VIEW)



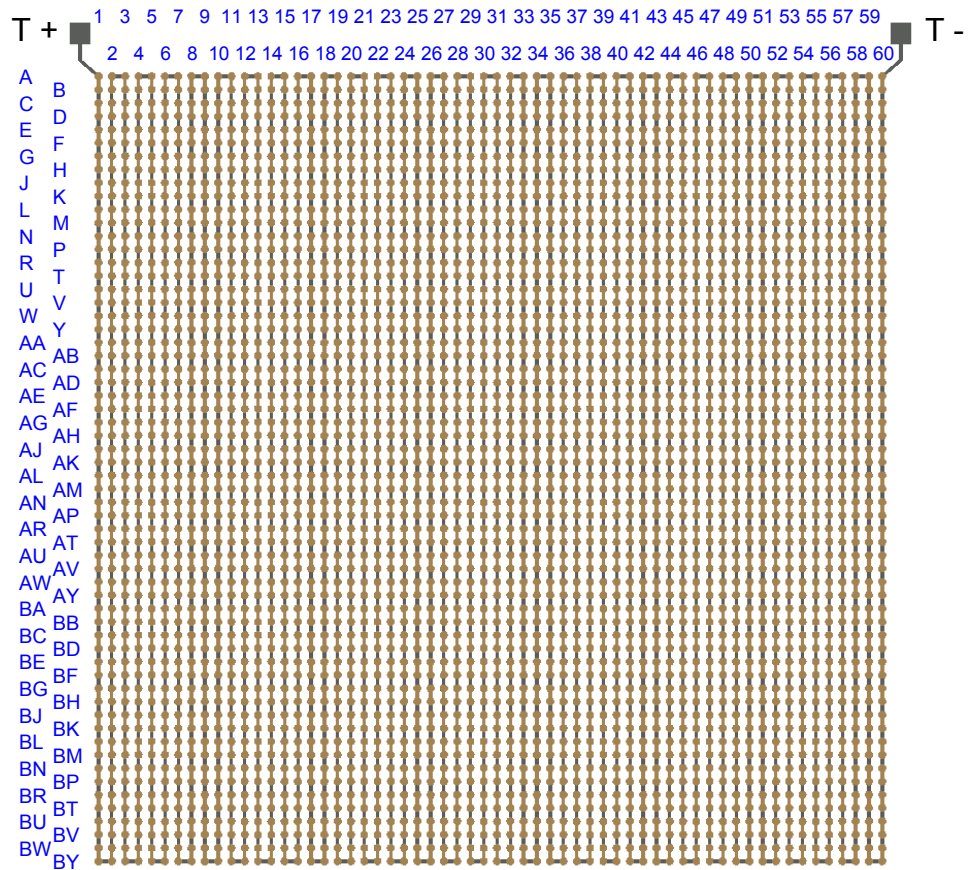
Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.355mm (14 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm (5 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.28mm (11 MIL).

TopLine®			
TITLE		LBGA3600T.5-DC609 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	556091	A
DO NOT SCALE DRAWING			SHEET 2 OF 3



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.355mm (14 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm (5 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.28mm (11 MIL).

TopLine®			
TITLE		LBGA3600T.5-DC609 DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	556091	A
DO NOT SCALE DRAWING			SHEET 3 OF 3